

Final Product Change Notification

202106009F01

Issue Date: 14-Jul-2021
Effective Date: 27-Oct-2021

Here's your personalized quality information concerning products Premier Farnell PLC purchased from Nexperia.
 For More details Please Contact your respective Nexperia CSR/AM.



Change Category

- | | | | | |
|---|--|--|---|---|
| <input checked="" type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

Change of back side metallization thickness and introduction of new EMCs in SOT23



Details of this Change

The back side metallization thickness will be changed from 2.15 µm to 1.75 µm.
 The change of the back side metallization thickness is combined with the introduction of additional EMCs (epoxy mold compounds) GR646CHN, CV4112 and E500HK.

Following the details:

Current Products

- back side metallization thickness 2.15 µm
- epoxy mold compound: GR646 (where affected) and E500HK (where affected)

Changed Products

- back side metallization thickness 1.75 µm
- epoxy mold compound: GR646 (where affected), CV4112 (where affected), E500HK and GR646CHN

Please find more information in the files linked below:

https://gcm.nexperia.com/change-notification-epcn/SQR_202106009F01.pdf

https://gcm.nexperia.com/change-notification-epcn/202106009F01_DeQuMa_PCN-Form.zip

Why do we Implement this Change

- to increase efficiency of volume production
- to increase flexibility and volume ramp-up

Identification of Affected Products

Changed product can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 08-Aug-2021.

Production

Planned first shipment 01-Nov-2021

Impact

No impact to the products' functionality anticipated.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 13-Aug-2021. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address pcn@nexperia.com

In case of distribution, please contact your distribution partner.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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